

Title (en)

Splitting method for brittle materials

Title (de)

Teilungsverfahren für spröde Materialien

Title (fr)

Procédé de fendage pour des matériaux cassants

Publication

EP 2058100 A1 20090513 (EN)

Application

EP 07021572 A 20071106

Priority

EP 07021572 A 20071106

Abstract (en)

A method for the splitting of a wafer from a body (1) of material capable of undergoing thermally induced fracture, characterized in that a source of cooling (4,15) is used to extract heat from the body (1) of material along a line or strip which progressively moves from one side of the body (1) to an opposite side thereof.

IPC 8 full level

B28D 1/22 (2006.01); **B28D 5/00** (2006.01)

CPC (source: EP)

B28D 1/221 (2013.01); **B28D 5/0011** (2013.01)

Citation (search report)

- [A] DE 3403826 A1 19850808 - SIEMENS AG [DE]
- [A] EP 0729815 A1 19960904 - SHINETSU HANDOTAI KK [JP]

Cited by

DE102010013549A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA HR MK RS

DOCDB simple family (publication)

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